Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP 2011xi IPS LED Backlit Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screw driver of &quot;+&quot; type</td>
<td>200mm</td>
</tr>
<tr>
<td>Description #2 Hexagonal nut screw driver for DVI and D-SUB connector</td>
<td>200mm</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External Electric Cables Dissecting Process
2. Remove Stand, Base, Hinge From Display
3. Remove Rear Cover From Display Head
4. Remove KEPC board From Front Cover
5. Remove Mainframe & Panel
6. Remove connecting wire off from Panel
7. Remove Front Cover & Panel
8. Remove connecting wire off Mainboard
9. Remove Mainframe & Mainboard
10. Remove Stand & Base
11.  
12.  

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pls. refer the attached:
HP- 2011xi

Disassembly Process

From: Clean.zhang
Date: Jan.-31-12
1. Remove Cable From Display Head.

2. Dissecting to Complete.
1. Demount Stand & Remove Stand Base From Display.
1. Take Screw(*) 2 from Rear Cover.

2. Take hinge cover from Rear Cover.

2. Take Screw(*) 3 from Rear Cover, and remove hinge off Rear Cover.

4. Turn up Display Head.

2. Turn over Display Head.

3. Toward the arrowhead, take the Rear Cover from the Front Cover.

4. Remove Rear Cover.
Remove KEPC board from Front Cover

1. Take the KEPC assembly from the Front Cover.

2. Remove Connector off from KEPC board.
1. Remove Connector off from Main board & Panel.

2. Remove the Conductive Tape from Mainframe.

3. Remove the Conductive Tape from Mainframe.

4. Take Screw(*2) from Mainframe.
1. Remove the adhesive tape.

2. Pull out the electronic wire of Panel.
1. Remove Mainframe & Panel.

2. Remove Insulator Sheet off from panel.

3. Turn up Panel, and remove the Front Cover off from Panel.

4. Dissecting to complete.
1. Pull out FFC & KEPC wire of Main Bd.

2. Remove the connecting wire off from Main Bd.
1. Take Screw(*4 or 2) from Mainframe.

2. Take Screw(*2) from Main Bd.

3. Remove the Main Bd off from Mainframe, dissecting to complete.
1. Take Stand assembly.

2. Pinch the limit RIB of Base.

3. Remove the Stand off from the Base, dissecting to complete.
Thank You!